

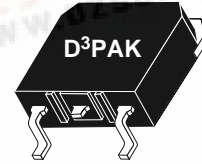


# APT5020SVFR

500V 26A 0.200Ω

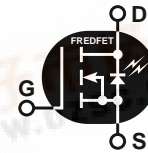
## POWER MOS V<sup>®</sup>

FREDFET



Power MOS V<sup>®</sup> is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V<sup>®</sup> also achieves faster switching speeds through optimized gate layout.

- Fast Recovery Body Diode
- Lower Leakage
- Faster Switching
- 100% Avalanche Tested
- Surface Mount D<sup>3</sup>PAK Package



### MAXIMUM RATINGS

All Ratings: T<sub>C</sub> = 25°C unless otherwise specified.

Symbol	Parameter	APT5020SVFR	UNIT
V <sub>DSS</sub>	Drain-Source Voltage	500	Volts
I <sub>D</sub>	Continuous Drain Current @ T <sub>C</sub> = 25°C	26	Amps
I <sub>DM</sub>	Pulsed Drain Current <sup>①</sup>	104	
V <sub>GS</sub>	Gate-Source Voltage Continuous	±30	Volts
V <sub>GSM</sub>	Gate-Source Voltage Transient	±40	
P <sub>D</sub>	Total Power Dissipation @ T <sub>C</sub> = 25°C	300	Watts
	Linear Derating Factor	2.4	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to 150	°C
T <sub>L</sub>	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I <sub>AR</sub>	Avalanche Current <sup>①</sup> (Repetitive and Non-Repetitive)	26	Amps
E <sub>AR</sub>	Repetitive Avalanche Energy <sup>①</sup>	30	mJ
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>④</sup>	1300	

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage (V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA)	500			Volts
I <sub>D(on)</sub>	On State Drain Current <sup>②</sup> (V <sub>DS</sub> > I <sub>D(on)</sub> × R <sub>DS(on)</sub> Max, V <sub>GS</sub> = 10V)	26			Amps
R <sub>DS(on)</sub>	Drain-Source On-State Resistance <sup>②</sup> (V <sub>GS</sub> = 10V, 0.5 I <sub>D(Cont.)</sub> )			0.20	Ohms
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0V)			250	μA
	Zero Gate Voltage Drain Current (V <sub>DS</sub> = 0.8 V <sub>DSS</sub> , V <sub>GS</sub> = 0V, T <sub>C</sub> = 125°C)			1000	
I <sub>GSS</sub>	Gate-Source Leakage Current (V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V)			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage (V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1.0mA)	2		4	Volts

**CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

### DYNAMIC CHARACTERISTICS

APT5020SVFR

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		3700	4440	pF
$C_{oss}$	Output Capacitance			510	715	
$C_{rss}$	Reverse Transfer Capacitance			200	300	
$Q_g$	Total Gate Charge ③	$V_{GS} = 10V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_D [\text{Cont.}] @ 25^\circ\text{C}$		150	225	nC
$Q_{gs}$	Gate-Source Charge			25	37	
$Q_{gd}$	Gate-Drain ("Miller") Charge			70	105	
$t_{d(on)}$	Turn-on Delay Time	$V_{GS} = 15V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_D [\text{Cont.}] @ 25^\circ\text{C}$ $R_G = 1.8\Omega$		12	25	ns
$t_r$	Rise Time			10	20	
$t_{d(off)}$	Turn-off Delay Time			50	75	
$t_f$	Fall Time			8	15	

### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
$I_S$	Continuous Source Current (Body Diode)			26	Amps
$I_{SM}$	Pulsed Source Current ① (Body Diode)			104	
$V_{SD}$	Diode Forward Voltage ② ( $V_{GS} = 0V, I_S = -I_D [\text{Cont.}]$ )			1.3	Volts
$dv/dt$	Peak Diode Recovery $dv/dt$ ⑤			5	V/ns
$t_{rr}$	Reverse Recovery Time ( $I_S = -I_D [\text{Cont.}], di/dt = 100A/\mu s$ )	$T_j = 25^\circ\text{C}$		250	ns
		$T_j = 125^\circ\text{C}$		500	
$Q_{rr}$	Reverse Recovery Charge ( $I_S = -I_D [\text{Cont.}], di/dt = 100A/\mu s$ )	$T_j = 25^\circ\text{C}$		1.3	$\mu\text{C}$
		$T_j = 125^\circ\text{C}$		4.5	
$I_{RRM}$	Peak Recovery Current ( $I_S = -I_D [\text{Cont.}], di/dt = 100A/\mu s$ )	$T_j = 25^\circ\text{C}$		12	Amps
		$T_j = 125^\circ\text{C}$		18	

### THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.42	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum junction temperature.

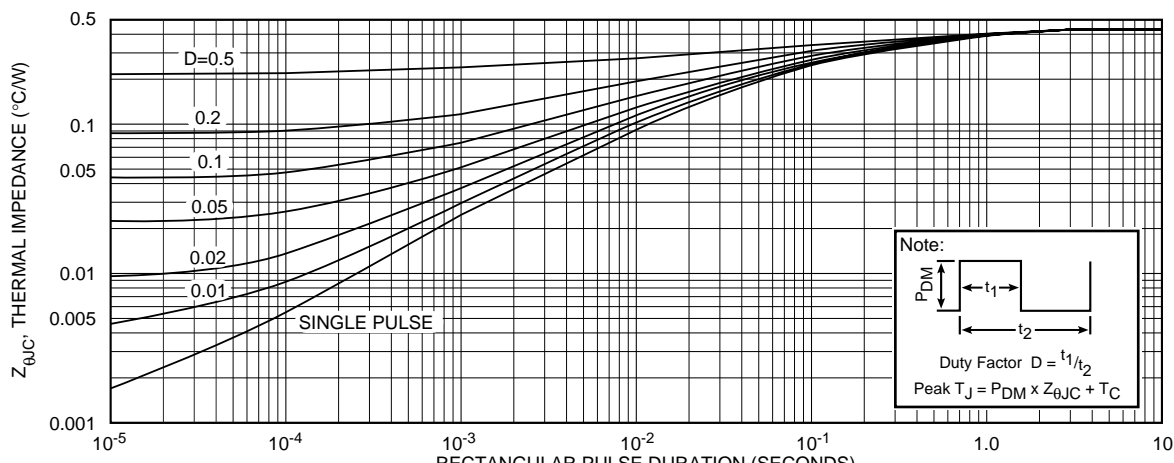
② Pulse Test: Pulse width < 380  $\mu\text{s}$ , Duty Cycle < 2%

③ See MIL-STD-750 Method 3471

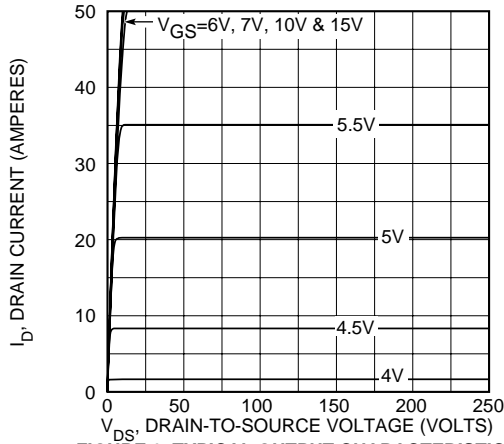
④ Starting  $T_j = +25^\circ\text{C}$ ,  $L = 3.85\text{mH}$ ,  $R_G = 25\Omega$ , Peak  $I_L = 26\text{A}$

⑤  $I_S \leq -I_D [\text{Cont.}], di/dt = 100A/\mu s, V_{DD} \leq V_{DSS}, T_j \leq 150^\circ\text{C}, R_G = 2.0\Omega, V_R = 200V$ .

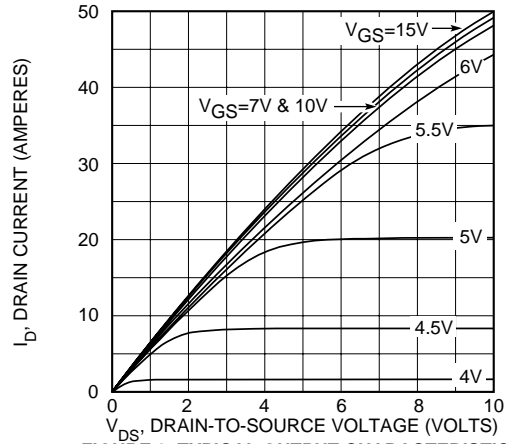
APT Reserves the right to change, without notice, the specifications and information contained herein.



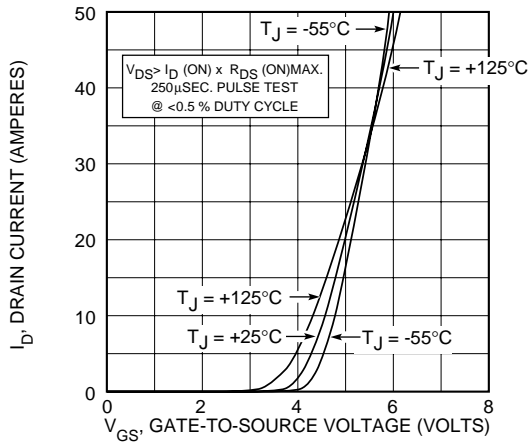
**APT5020SVFR**



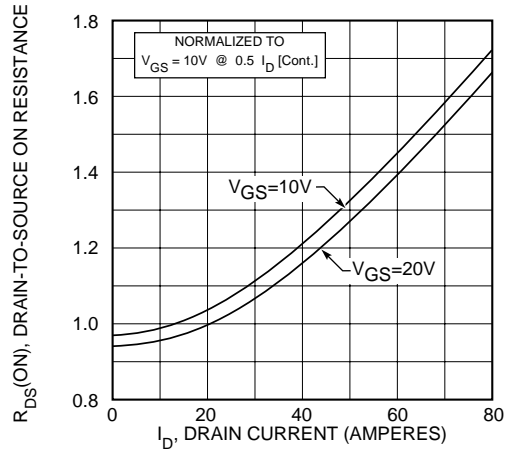
**FIGURE 2, TYPICAL OUTPUT CHARACTERISTICS**



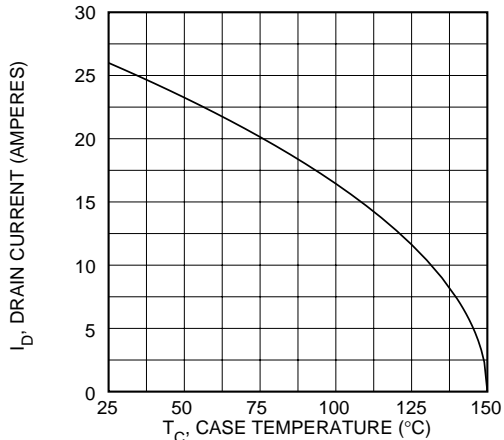
**FIGURE 3, TYPICAL OUTPUT CHARACTERISTICS**



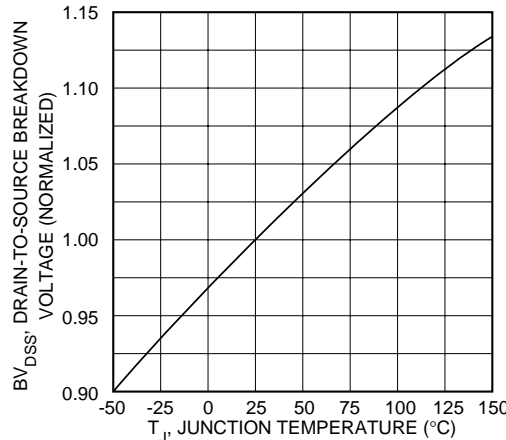
**FIGURE 4, TYPICAL TRANSFER CHARACTERISTICS**



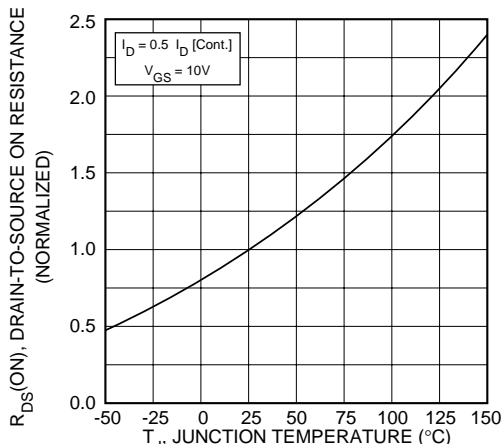
**FIGURE 5,  $R_{DS(ON)}$  vs DRAIN CURRENT**



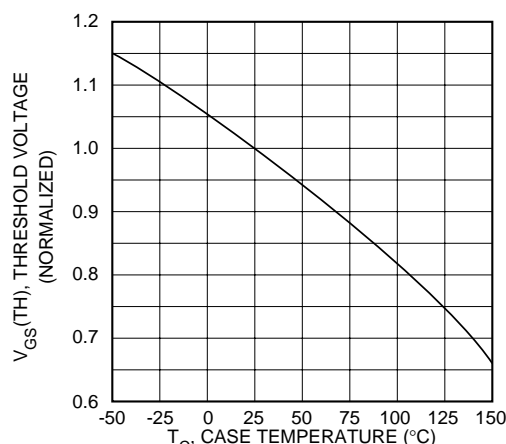
**FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE**



**FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE**



**FIGURE 8, ON-RESISTANCE vs. TEMPERATURE**



**FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE**

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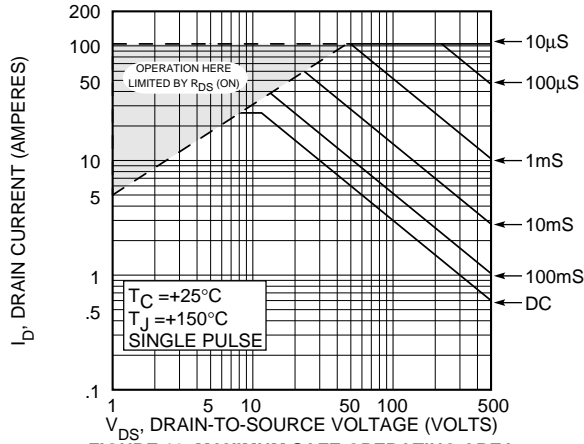


FIGURE 10, MAXIMUM SAFE OPERATING AREA

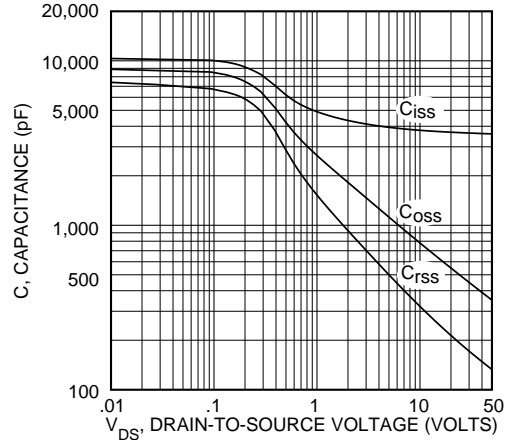


FIGURE 11, TYPICAL CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

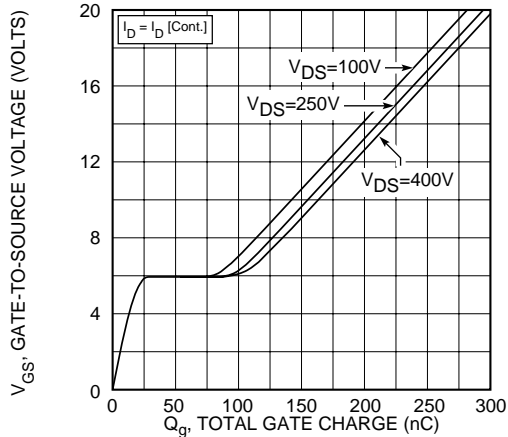


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

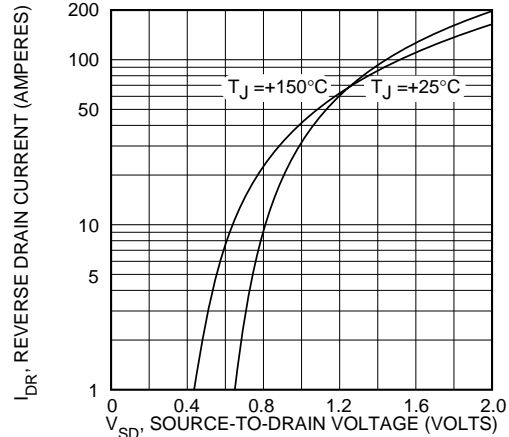


FIGURE 13, TYPICAL SOURCE-DRAIN DIODE FORWARD VOLTAGE

## D<sup>3</sup>PAK Package Outline

